Specification No. JELF243A-0069D-01

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Reference Specification

Part Description:	Chip Coil (Chip Inductors)
MURATA Part No:	LQH44PN□□□□P0L
RoHS reg	gulation conformity parts.

Technical Dept.

Prepared by

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(Company name / Division)

CHIP COIL (CHIP INDUCTORS) LQH44PN□□□□P0L REFERENCE SPECIFICATION

1.Scope

This reference specification applies to LQH44PN Series, Chip coil (Chip Inductors).

2.Part Numbering

(ex) LQ H Oroduct ID Structure Dimension (L × W) Applications and Characteristics N Applications Category Inductance Tolerance Features Electrode Packaging L:Taping

3.Rating

Operating Temperature Range.
 Storage Temperature Range.
 -40 to +85°C
 -40 to +85°C

		Inductance		DC Resistance	Self Resonant	Rated Current (mA)	
Customer Part Number	MURATA Part Number	(µH)	Tolerance	(Ω)		*1 (Based on Inductance change)	*2 (Based on Temperature rise)
	LQH44PN1R0NP0L	1.0	N:±30	0.030±20%	90	2950	2450
	LQH44PN2R2MP0L	2.2		0.049±20%	70	2500	1800
	LQH44PN3R3MP0L	3.3		0.065±20%	50	2100	1770
	LQH44PN4R7MP0L	4.7	M:±20	0.08±20%	40	1700	1700
	LQH44PN6R8MP0L	6.8	IVI.±2U	0.12±20%	35	1400	1340
	LQH44PN100MP0L	10		0.16±20%	25	1150	1170
	LQH44PN220MP0L	22		0.37±20%	17	800	790

^{*1:} When applied rated current to the Products, Inductance will be within ±30% of nominal Inductance value.

4. Testing Conditions

《Unless otherwise specified》

Temperature : Ordinary Temperature (15 to 35°C)

Humidity : Ordinary Humidity (25 to 85 %(RH))

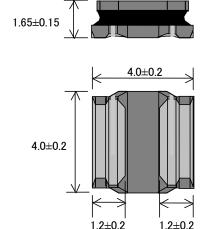
《In case of doubt》

Temperature : 20 ± 2°C

Humidity : 60 to 70 %(RH)

Atmospheric Pressure: 86 to 106 kPa

5.Appearance and Dimensions



※No Marking.

(in mm)

■Unit Mass (Typical value) 0.10 g

^{*2:} When applied rated current to the Products, self-generation of heat will rise to 40°C or less.



6.Electrical Performance

No.	Item	Specification	Test Method
6.1	Inductance	Inductance shall meet item 3.	Measuring Equipment : Agilent 4284A or equivalent
			Measuring Frequency:1MHz
6.2	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment:Digital multi meter
6.3	Self Resonant	S.R.F shall meet item 3.	Measuring Equipment: Agilent 4291A or equivalent
	Frequency(S.R.F)		

7.Mechanical Performance

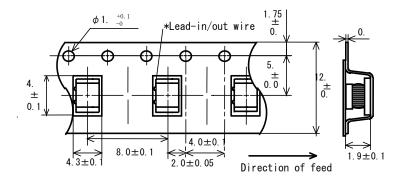
No.	Item	Specification	Test Method	
7.1	Shear Test	Chip coil shall not be damaged.	Substrate: Glass-epoxy substrate	
			Applied Direction: Chip coil _	
			F F	
			Force: 10N Substrate	
			Hold Duration: 5±1s	
7.2	Bending Test		Substrate: Glass-epoxy substrate	
			(100 × 40 × 1.0mm)	
			Speed of Applying Force: 0.5mm / s	
			Deflection: 3mm	
			Hold Duration: 5seconds.	
			Pressure jig R230 F Deflection 45	
7.3	Vibration		Oscillation Frequency: 10~2000~10Hz for 20minutes	
			Total Amplitude: 1.5mm	
			Testing Time: A period of 2 hours in each of	
			3 mutually perpendicular directions.	
			(Total 6 hours)	
7.4	Solderability	The wetting area of the electrode	Flux: Ethanol solution of rosin,25(wt)%	
		shall be at least 90% covered with	(Immersed for 5s to 10s)	
		new solder coating.	Solder: Sn-3.0Ag-0.5Cu	
			Pre-Heating: 150±10°C / 60 to 90seconds	
			Solder Temperature: 240±5°C	
			Immersion Time: 3±1 s	
7.5	Resistance to	Appearance:No damage	Flux: Ethanol solution of rosin,25(wt)%	
	Soldering	Inductance Change: within ±10%	(Immersed for 5s to 10s)	
	Heat		Solder: Sn-3.0Ag-0.5Cu	
			Pre-Heating: 150±10°C / 60 to 90seconds	
			Solder Temperature: 270±5°C	
			Immersion Time: 10±1 s	
			Then measured after exposure in the room condition	
			for 24±2 hours.	

8.Environmental Performance (It shall be soldered on the substrate.)

No.	Item	Specification	Test Method
8.1	Heat Resistance	Appearance:No damage	Temperature:85±2°C
		Inductance Change: within ± 10%	Time: $1000 \pm_0^{48}$ hours
		DC Resistance Change:	Then measured after exposure in the room
		within ± 10%	condition for 24±2 hours.
8.2	Cold Resistance		Temperature:-40±2°C
			Time:1000±48 hours
			Then measured after exposure in the room
			condition for 24±2 hours.
8.3	Humidity		Temperature:70±2°C
			Humidity:90~95%(RH)
			Time: $1000 \pm_0^{48}$ hours
			Then measured after exposure in the room
			condition for 24±2 hours.
8.4	Temperature		1 cycle:
	Cycle		1 step: -40±2°C / 30±3 minutes
			2 step:Ordinary temp. / 10 to 15 minutes
			3 step:+85±2°C / 30±3 min
			4 step: Ordinary temp. / 10 to 15 minutes
			Total of 10 cycles
			Then measured after exposure in the room
			condition for 24±2 hours.

9. Specification of Packaging

9.1 Appearance and Dimensions of plastic tape



(in mm)

Dimension of the Cavity is measured at the bottom side.

9.2 Specification of Taping

- (1) Packing quantity (standard quantity)
 - 1,000 pcs / reel
- (2) Packing Method

Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.

- (3) Sprocket hole
 - Sprocket hole shall be located on the left hand side toward the direction of feed.
- (4) Spliced point
 - Plastic tape and Cover tape has no spliced point.
- (5) Missing components number

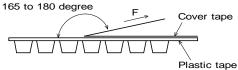
Missing components number within 0.1 % of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

9.3 Pull Strength

Embossed carrier tape	10N min.
Cover tape	5N min.

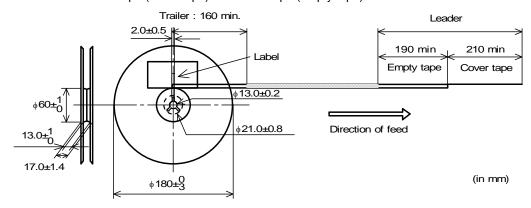
9.4 Peeling off force of cover tape

Speed of Peeling off	300mm/min	
Peeling off force	0.2 to 0.7N	
	(minimum value is typical)	



9.5 Dimensions of Leader-tape, Trailer and Reel

There shall be leader-tape (cover tape) and trailer-tape (empty tape) as follows.



9.6 Marking for reel

Customer part number, MURATA part number, Inspection number(*1), RoHS discrimination(*2), Quantity etc · · ·

*1) <Expression of Inspection No.>

 $\frac{\square \square}{(1)} \quad \frac{OOOO}{(2)} \quad \frac{\times \times \times}{(3)}$

(1)Factory Code

(2) Date First digit : Year / Last digit of year

Second digit : Month / Jan. to Sep. \rightarrow 1 to 9, Oct. to Dec. \rightarrow O, N, D

Third, Fourth digit: Day

(3) Serial No.

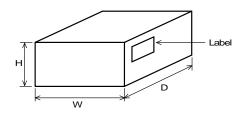
*2) « Expression of RoHS discrimination » ROHS – \underline{Y} ($\underline{\triangle}$) (1) (2)

- (1) RoHS regulation conformity parts.
- (2) MURATA classification number

9.7 Marking for Outside package (corrugated paper box)

Customer name, Purchasing order number, Customer part number, MURATA part number, RoHS discrimination(*2) ,Quantity, etc ···

9.8. Specification of Outer Case



Outer Case Dimensions (mm)		nsions	Standard Reel Quantity in Outer Case
W	D	Н	(Reel)
186	186	93	4

* Above Outer Case size is typical. It depends on a quantity of an order.



10. A Caution

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

(1) Aircraft equipment

(7) Traffic signal equipment

(2) Aerospace equipment

(8) Disaster prevention / crime prevention equipment

(3) Undersea equipment

(9) Data-processing equipment

(4) Power plant control equipment

(10) Applications of similar complexity and /or reliability requirements

(5) Medical equipment

to the applications listed in the above

(6) Transportation equipment (vehicles, trains, ships, etc.)

11. Notice

This product is designed for solder mounting.

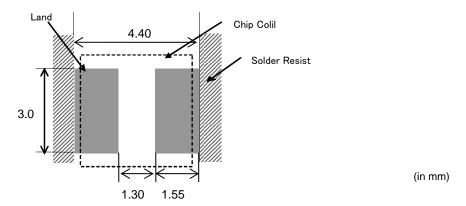
Please consult us in advance for applying other mounting method such as conductive adhesive.

11.1 Land pattern designing (Reflow Soldering)

Recommended land patterns for reflow soldering are as follows:

These have been designed for Electric characteristics and solderability.

Please follow the recommended patterns as designated performance(s), including solderability, may be affected.



11.2 Flux, Solder

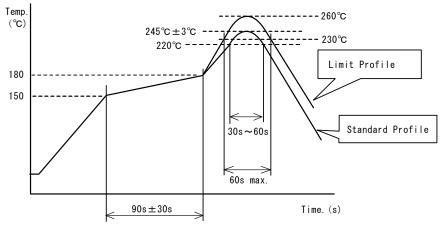
Flux	 Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
	Don't use water-soluble flux.
Solder	• Use Sn-3.0Ag-0.5Cu solder.
Solder	• Standard thickness of solder paste : 100μ m to 150μ m

11.3 Soldering conditions (Reflow)

- Pre-heating should be in such a way that the temperature difference between solder and product surface
 is limited to 100°C max. Cooling into solvent after soldering also should be in such a way that the
 temperature difference is limited to 100°C max.
 Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows.
 The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.

soldering profile

Reflow soldering profile



	Standard Profile	Limit Profile		
Pre-heating	150~180°C 、90s±30s			
Heating	above 220°C、30s∼60s	above 230°C、60s max.		
Peak temperature	245±3°C	260°C,10s		
Cycle of reflow	2 times	2 times		

11.4 Reworking with soldering iron.

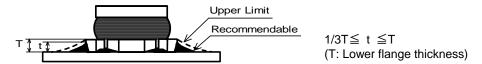
The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C,1 min
Tip temperature	350°C max.
Soldering iron output	80W max.
Tip diameter	φ 3mm max.
Soldering time	3(+1,-0)s
Times	2 times

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the products due to the thermal shock.

11.5 Solder Volume

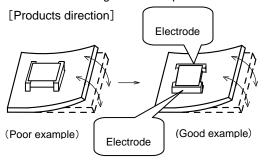
- · Solder shall be used not to be exceed the upper limits as shown below.
- · Accordingly increasing the solder volume, the mechanical stress to Chip is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.



11.6 Product's location

The following shall be considered when designing and laying out P.C.B.'s.

(1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.



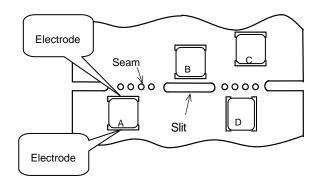
The electorode part of the products should be located like the picture to the mechanical stress.

P7/8

(2) Products location on P.C.B. separation

Products (A,B,C,D) shall be located carefully so that products are not subject to the mechanical stress due to warping the board.

Because they may be subjected the mechanical stress in order of $A>C>B \cong D$.



11.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1) Cleaning temperature shall be limited to 60°C max.(40°C max for IPA.)
- (2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.

Power: 20 W / I max. Frequency: 28kHz to 40kHz Time: 5 minutes max.

- (3) Cleaner
 - 1. Alternative cleaner
 - Isopropyl alcohol (IPA)
 - 2. Aqueous agent
 - PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.

In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.

(5) Other cleaning

Please contact us.

11.8 Resin coating

The inductance value may change due to high cure-stress of resin to be used for coating/molding products. An open circuit issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to open circuit. So, please pay your careful attention when you select resin in case of coating/molding the products with the resin.Prior to use the coating resin, please make sure no reliability issue is observed by evaluating products mounted on your board.

11.9 Caution for use

- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core

11.10 Storage and Handling Requirements

(1) Storage period

Use the products within 12 months after delivered. Solderability should be checked if this period is exceeded.

(2) Storage conditions

• Products should be stored in the warehouse on the following conditions.

Temperature : -10 ~ 40°C

Humidity : 15 to 85% relative humidity No rapid change on temperature and humidity The electrode of the products is coated with solder. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.

- Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.

(3) Handling Condition

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.



12. **A** Note

- (1)Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2)You are requested not to use our product deviating from the reference specifications.
- (3)The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering